

## **DRAWINGS**

Fig. 1

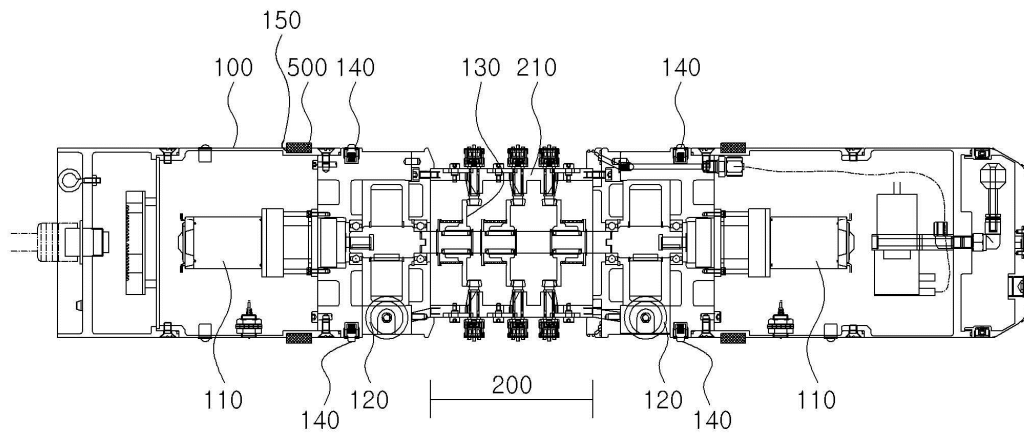


Fig. 2

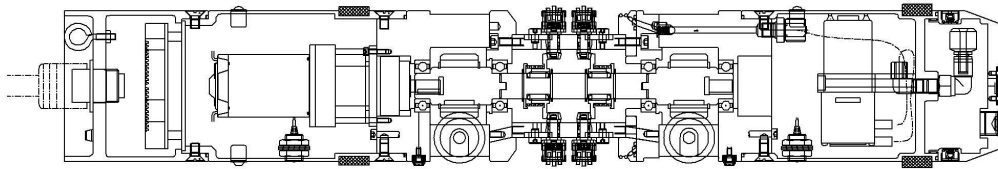


Fig. 3

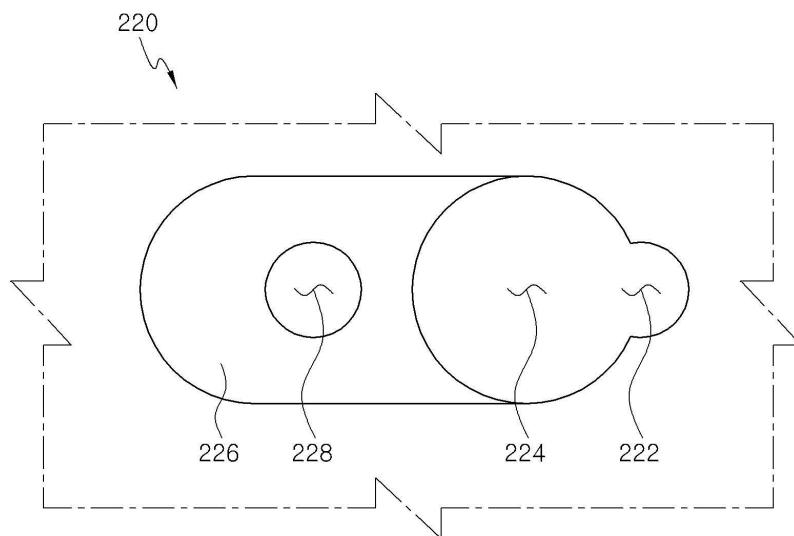


FIG. 1 is a schematic diagram of a multi-layer printed circuit board assembly 200. The assembly includes multiple layers (210, 226, 228) and various components like vias (300, 400), pads (410, 420, 422, 430), and conductive traces (310). A detailed view of a via structure 372 is shown, highlighting its internal features.

Fig. 5

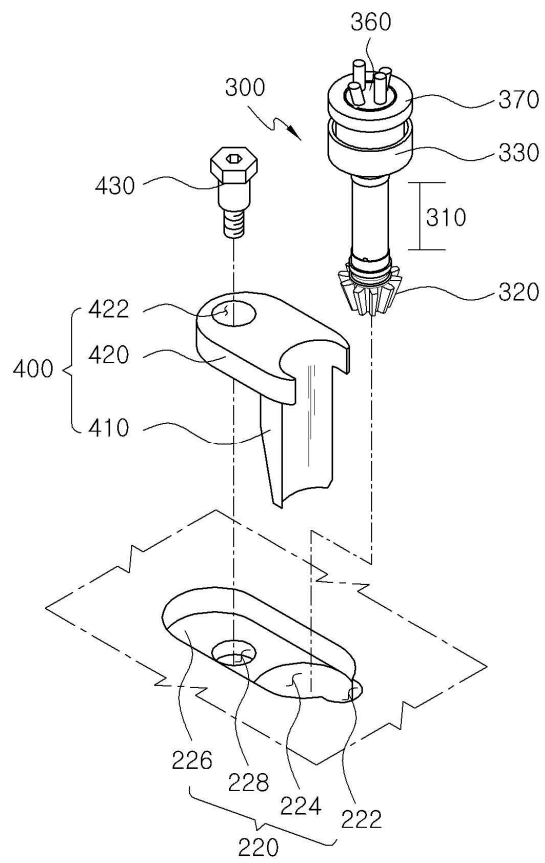


Fig. 6

